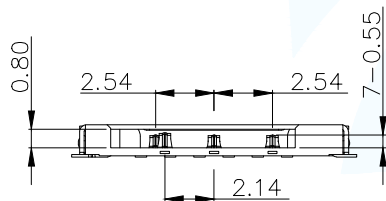
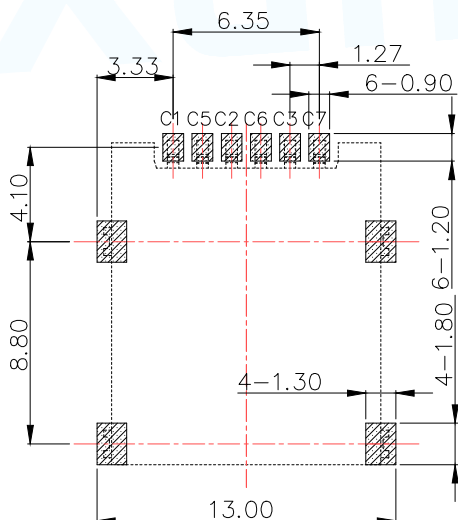


NOTES:

- MATERIAL:
 - Housing: High Temperature Thermoplastic UL94V-0; Color Black.
 - Terminal: Copper Alloy, T=0.12mm.
 - Shell: Stainless Steel, T=0.20mm.
- FINISH:
 - Terminal: Plated Gold on The Contact Area and Solder Tails
 - Peg: Plated Gold on the Solder Tails.
- SPECIALITY:
 - Rated current: 0.5A
 - Rated voltage: 50V
 - Contact Resistance: 80mΩMAX
 - Insulation Resistance: 100MΩMIN 100V DC
 - Dielectric withstanding voltage: 100V AC.
 - Solder ability: 245±5°C, 5±0.5s.
 - Operating condition: Temperature: -30°C~+80°C Humidity: 80% R.H MAX

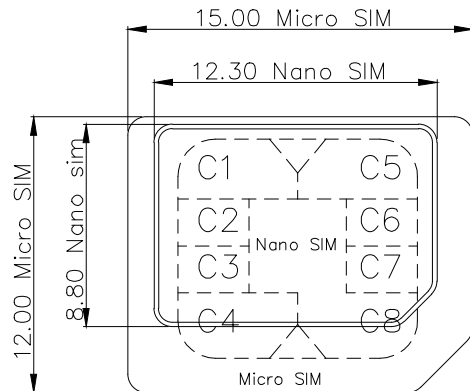


NANO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A



▨ PAD AREA
 ■ KEEP OUT AREA

RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05



③	TERMINAL	6	C5210-EH, T=0.12	Au 3u" PLATING
②	BASE INSULATOR	1	LCP+GF30%	BLACK
①	SHELL	1	SUS304-H, T=0.15	AU/NI PLATING
NO.	PART NAME	Q'TY	DESCRIPTION	NOTE

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co., Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE: 6PIN 1.4H HINGE NANO SIM CARD CONN.	
DECIMALS:	ANGLES:	PAR	SMN-305
X.: ±0.50	X.°: ±2'	DWN	helen
X.X: ±0.20	X.X: ±1'	CHKD	
X.XX: ±0.10		APVD	
CUSTOMER COPY		SCALE: 1:1	UNIT: MM
		SIZE: A4	SHEET: 1F1
			REV: A